

**128-04****HIGH TEMPERATURE THERMALLY CONDUCTIVE POLYIMIDE ADHESIVE**

DESCRIPTION: 128-04 is a multipurpose polyimide adhesive suitable for applications where high temperature and flammability requirements need to be met. Due to its low ionic content 128-04 is suitable for microelectronics grade die attach applications. The cure schedule allows for rapid processing and the resulting bond exhibits excellent thermal stability and adhesion at elevated temperatures.

TYPICAL CURED PROPERTIES:

Viscosity (cps)	20,000 – 30,000
Thermal Conductivity (W/mK)	1.55
Glass Trans. Temp. (°C)	> 250
Hydrolytic Stability	Excellent
Useful Temperature Range (°C)	-55 to +250
Thermal Stability (°C)	325+
T-Shear Strength (psi)	>1250
CTE (@ 200°C)/°C	9.4×10^{-6}
Flexural strength (@ 200°C, PSI)	8,412
Flexural modulus (@ 200°C, PSI)	464,122
Flexural elongation (@ 200°C, %)	1.83

SUGGESTED HANDLING & CURING: 128-04 is ready to use as supplied. For best properties, apply adhesive to surfaces to be bonded and cure for one hour at 175°C with a subsequent post cure of five hours at 210°C. Good properties are obtained on a variety of substrates by curing at temperatures ranging from 130°C to 210°C. The end user is advised to experimentally determine temperature and time best suited for individual applications. Post curing may not be necessary in many applications.

STORAGE: 1 year at -5°C. It is advised to keep product frozen to keep filler suspended.

**Crystallization may occur during storage. Heating at 40-50°C for 15 minutes will re-melt crystals and make the product useable again.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 02/02/18 REVISION: A